IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIE	Material Composi © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	ials and Mfg Information					
upplier Inforn	nation														
Company name*			Company unique ID			τ	Unique ID Authority				Respon	Response Date*			
onsemi											2024-05	2024-05-16			
Contact Name		Title - Contact			1	Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
Request	Requester Item Number Mfr Iter		m Number Mfr Item Name				Effective Date Version M		Manufacturing Site		Weight*	UOM	Unit Type		
		NVMFS5C426NAFT1 T6-D3F 40V NFET G-YE		ET		2024-05-16	24-05-16 MYE			115.1458	mg	Each			
Ianufacturing	Proccess Informatio	n													
Terminal Plating / Grid Array Material T			erminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperature Max Time at 1		re Max Time at Peal	k Tempera	ture Numb	er of Reflow Cyc	cles			
Matte Tin (Sn) - annealed		C	CU Alloy 1		1		260		C	30	secor	nds 3			
omments															
vel 1 - maximum	time at peak temperature	during solo	dering is 10-3	0 seconds											
or more informati	on regarding material co	mposition r	olease refer to	page 3									-		

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Isability and the Company's remedies for issues that arise regarding information the Supplier provides in this fo										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	16.6715	mg	Supplier	Iron (Fe)	7439-89-6		0.0167	mg
			Supplier	Copper (Cu)	7440-50-8		16.6498	mg
			Supplier	Phosphorus (P)	7723-14-0		0.005	mg
Die	1.4031	mg	Supplier	Silicon (Si)	7440-21-3		1.4031	mg
Die Attach Solder	2.9239	mg	Supplier	Silver (Ag)	7440-22-4		0.0731	mg
			A	Lead (Pb)	7439-92-1	7a	2.7046	mg
			Supplier	Tin (Sn)	7440-31-5		0.1462	mg
Lead Frame	47.9421	mg	Supplier	Zinc (Zn)	7440-66-6		0.0575	mg
			Supplier	Iron (Fe)	7439-89-6		1.1266	mg
			Supplier	Copper (Cu)	7440-50-8		46.7435	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0144	mg
Mold Compound-Black	45.9588	mg		Epoxy resin	proprietary data		3.4469	mg
			Supplier	Phenolic Resin	Proprietary Data		1.149	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.4469	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2298	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		37.6862	mg
Plating	0.2183	mg	Supplier	Tin (Sn)	7440-31-5		0.2183	mg
Wire Bond - Cu	0.0281	mg	Supplier	Copper (Cu)	7440-50-8		0.0281	mg